



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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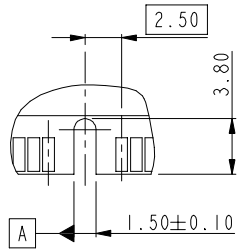
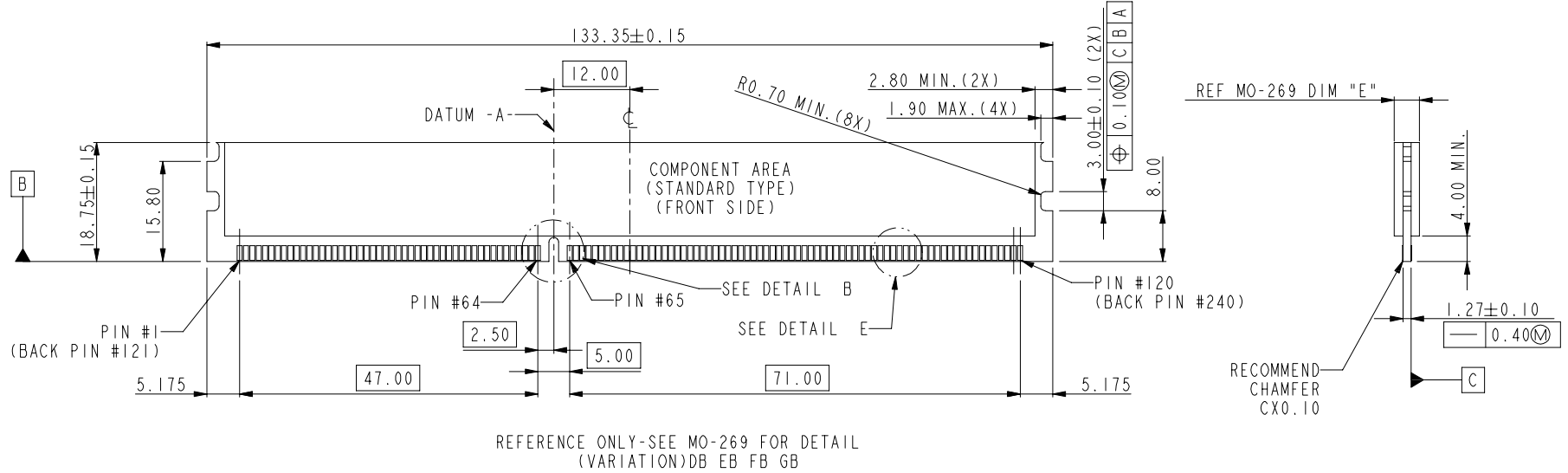
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



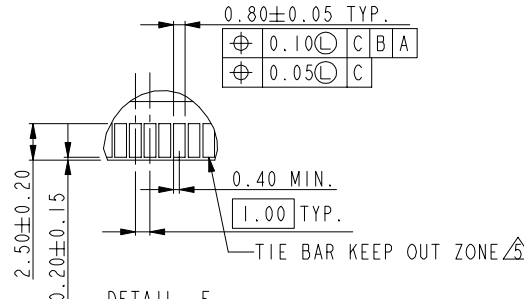




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DETAIL B  
SCALE 2.000



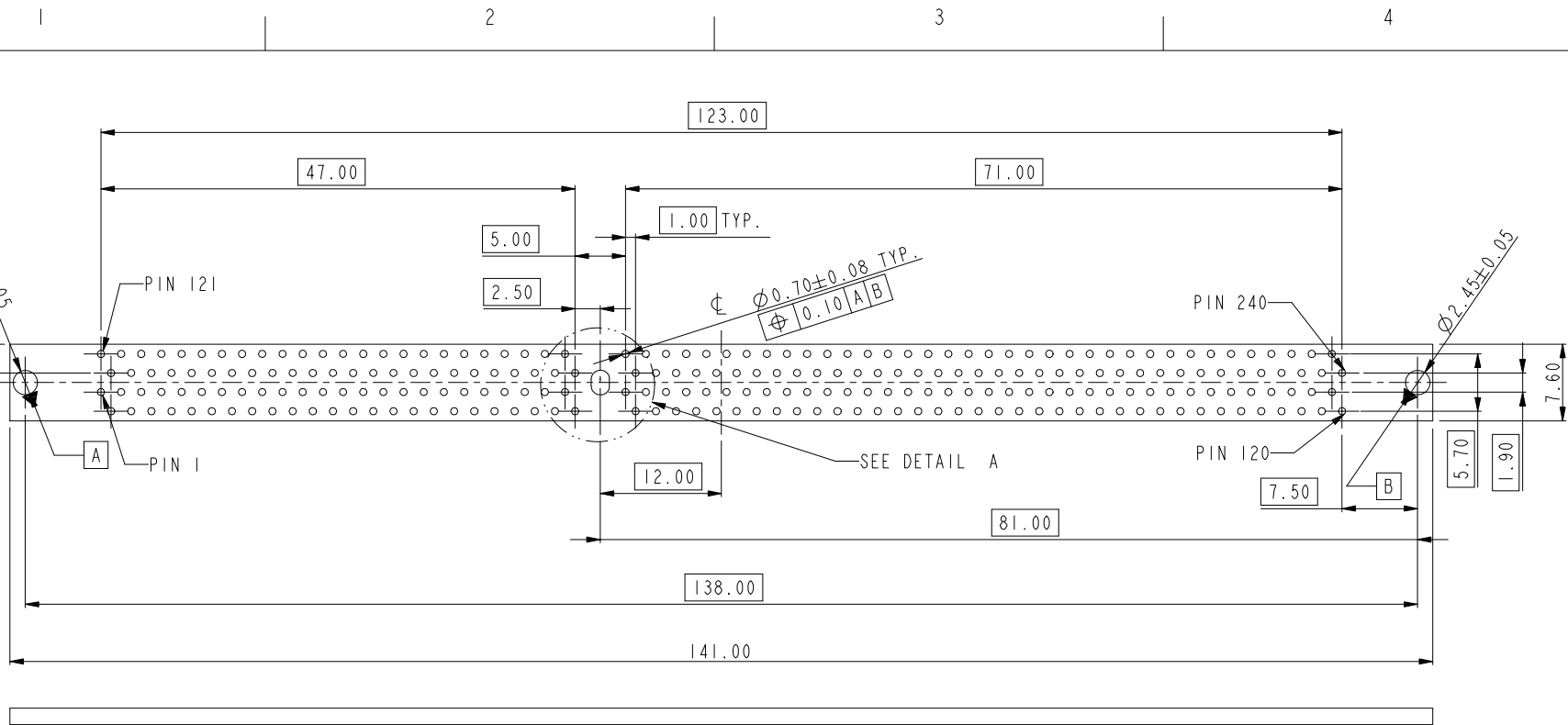
DETAIL E  
SCALE 2.000

www.fciconnect.com				surface <input checked="" type="checkbox"/>	tolerance std	projection	MM
TOLERANCES UNLESS OTHERWISE SPECIFIED						Scale 1.000	
Dr	STONE	LI	02/10/2015	ANGULAR	0.X	±0.38	size A4
Eng	STONE	LI	02/10/2015	LINEAR	0.XX	±0.25	ECN /
Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	Spec ref *
Appr	Collins	Lu	02/10/2015	Product family			
				title VERY LOW PROFILE (VLP) T.H. DDR3, 240P SOCKET (FOR RDIMM MOUDLE)		dwg no 10079192	
catalog no				CUSTOMER		sheet 2 of 4	

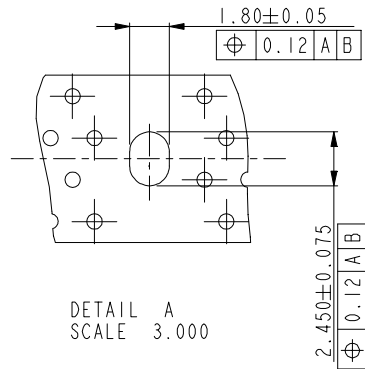


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REV F - 2006-04-17



RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



www.fciconnect.com				surface	-	tolerance std	projection	MM
				TOLERANCES UNLESS OTHERWISE SPECIFIED				Scale
Dr	STONE	LI	02/10/2015	ANGULAR	0.X	±0.38	size	A4
Eng	STONE	LI	02/10/2015	LINEAR	0.XX	±0.25	ECN	0.707
Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	ECN	/
Appr	Collins	Lu	02/10/2015	Product family	-	Spec ref	*	
		title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)			dwg no 10079192		Rev. K	
catalog no				-		CUSTOMER		sheet 3 of 4



10079192 - □ □ □ □

STYLE : MECHANICAL KEYING  
1 : 1.5 VOLT. W/ CENTER KEY

CONTACT & FORKLOCK LENGTH

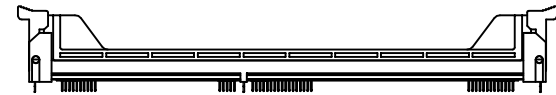
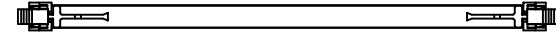
CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 mm (0.063")
11	3.18 mm	4.00 mm	2.36 mm (0.093")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2LF	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 1 : BLACK HOUSING + AMBER EJECTOR (NOTE. 11)
- 2 : BLACK HOUSING + BLACK EJECTOR
- 8 : IVORY HOUSING + IVORY EJECTOR
- 9 : IVORY HOUSING + BLACK EJECTOR
- 3 : BLUE HOUSING + IVORY EJECTOR
- △4 : BLACK HOUSING + IVORY EJECTOR + CAP



PRODUCT WITH CAP ILLUSTRATION

NOTES:

1. MATERIAL:  
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
TERMINAL: HIGH PERFORMANCE COPPER ALLOY  
METAL CLIP: COPPER ALLOY.
- △2 FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-486.
4. PACKAGING SPECIFICATION: GS-14-899.
- △5 FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
- △6 THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE. "R" MEANS FOR 'RDIMM' SOCKET.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X. (SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. AMBER EJECTOR OPTION IS ONLY FOR SOLDERING ENVIRONMENT TEMP. UNDER 170°C.
12. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.
13. THIS SOCKET CONTACT EOL RESISTANCE IS DESIGNED TO BE 20 mohm MAX.



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				TOLERANCES UNLESS OTHERWISE SPECIFIED			
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Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	ECN /
Appr	Collins	Lu	02/10/2015	Product family	-	Spec ref	*
FCI		title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)			dwg no 10079192		Rev. K
		catalog no -			CUSTOMER		sheet 4 of 4